

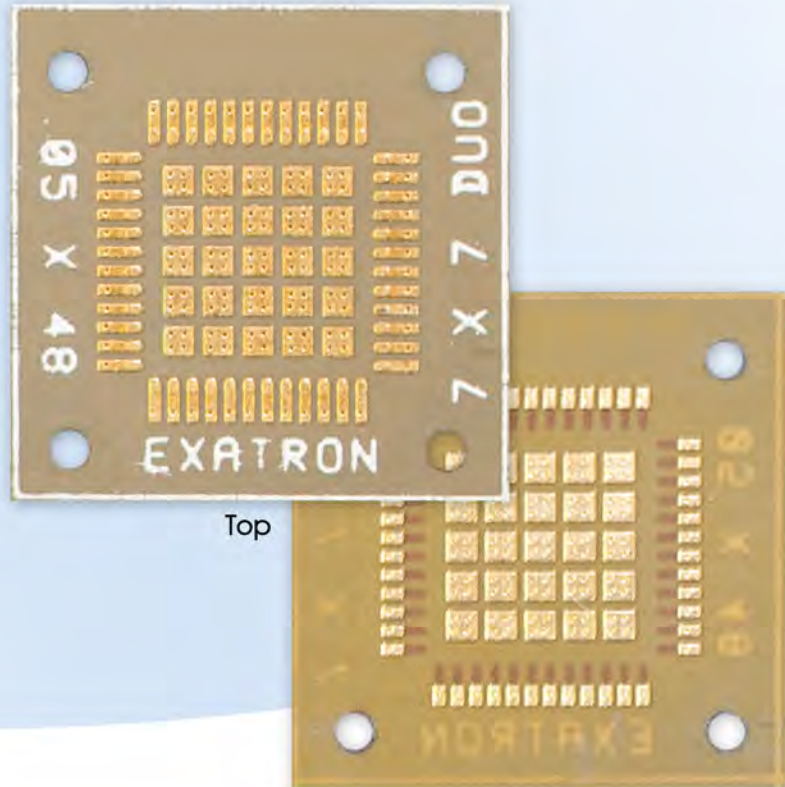
# exatron DUO INTERPOSER

COMPLIANT DIAMOND PARTICLE INTERCONNECT CONTACTS

Built-in mechanical compliance,  
with the shortest  
contact height  
of any socket  
on the market today



Selectively-plated  
bumps optional



Top

Bottom

- Diamond Particle Interconnect contact surface, top and bottom.
- 0.1mm (0.004") of mechanical compliance minimum.
- Less than 0.3mm (0.010") thick.
- -70° C to +200° C temperature range.
- Reliable performance, durable construction.

- Tested to 40GHz in RF applications.
- Works with MLF, QFN, and LCC leadless packages with up to 0.4mm pitch and all leaded packages.
- Matches any existing socket footprint.
- Many material choices available.
- Patented Exatron design (US patent 6,703,851).



2842 Alello Drive, San Jose, CA 95111  
1-800-EXA-TRON 1-408-629-7600 [www.exatron.com](http://www.exatron.com)



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Top side lead contact,  
copper-plated to 3 oz.

Top side ground slug contact,  
copper-plated to 2 oz.

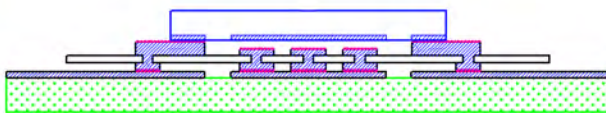


Bottom side lead contact,  
copper-plated to 2 oz.

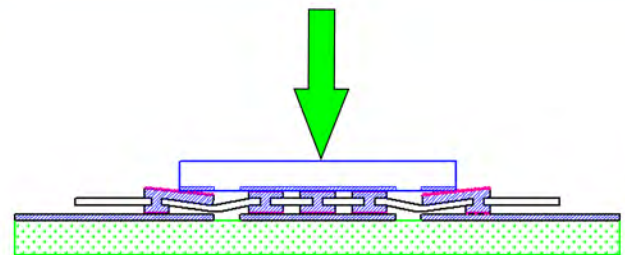
Air gap

Bottom side ground slug contact,  
copper-plated to 2 oz.

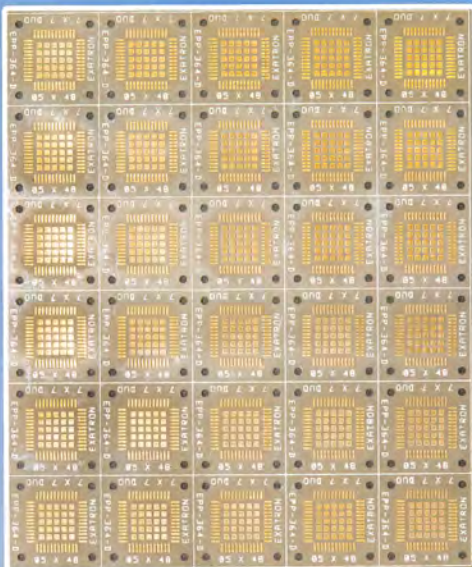
DUO Interposer Cross Section



DUT device at DUO Interposer socket -  
initial state

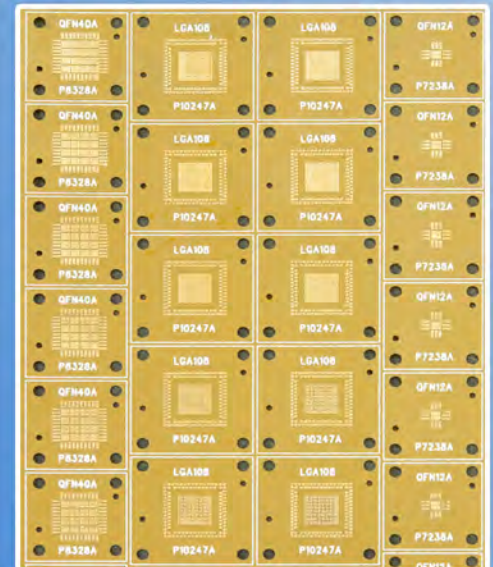


DUT device at DUO Interposer socket -  
after pressure is applied



Single Size Sheet

- Sold in sheets or as part of a complete test socket.
- Easily adapts to any rocker-type test socket footprint and tooling pin or bolt pattern.
- Visit [PISockets.com](http://PISockets.com) for information on other PI products.



Multiple Size Sheet



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